

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Christophe MALEVILLE et al.

Confirmation No.

Application No.:

Group Art Unit:

Filing Date:

Examiner:

For: METHOD FOR PREPARING A BONDING
SURFACE OF A SEMICONDUCTOR LAYER OF
A WAFER

Atty. Docket No.: 4717-10500

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

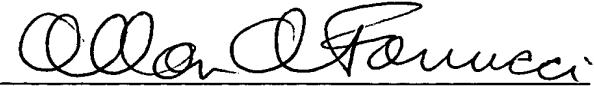
Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, enclosed are copies of (4) references for the Examiner's review and consideration. These references were cited in the International Search Report for this application and a copy is enclosed.

These references are listed on the enclosed Form PTO-1449. It is respectfully requested that these references be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee or certification is believed to be due for this submission since the references are being submitted concurrent with the filing of this application. Should any fees be required, however, please charge such fees to **Winston & Strawn LLP** Deposit Account No. 50-1814.

Respectfully submitted,

Date: 3-25-2004



Allan A. Fanucci (Reg. No. 30,256)

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Enclosures

| | | | | | | | |
|--|--|--|--|--|-----------------------|------------------|--|
| | | | | | ATTY. DOCKET NO.: | APPLICATION NO.: | |
| | | | | | 81421-4038 | | |
| | | | | | APPLICANT: | | |
| | | | | | Steen Ørsted ANDERSEN | | |
| | | | | | FILING DATE: | GROUP: | |
| | | | | | March 9, 2004 | | |

U.S. PATENT DOCUMENTS

| *EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
|-------------------|----|-----------------|---------|-----------------|-------|----------|----------------------------|
| | AA | 6,240,933 B1 | 6/2001 | Bergman | 134 | 1.3 | |
| | AB | 6,312,797 | 11/2001 | Yokokawa et al. | 428 | 336 | |
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| | AD | | | | | | |

FOREIGN PATENT DOCUMENTS

| | | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION | |
|--|----|-----------------|------|---------|-------|----------|-------------|----|
| | | | | | | | YES | NO |
| | AE | | | | | | | |
| | AF | | | | | | | |
| | AG | | | | | | | |
| | AH | | | | | | | |
| | AI | | | | | | | |

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

| | | |
|--|----|---|
| | AJ | Seiji Fujino et al., "Silicon Wafer Direct Bonding through the Amorphous Layer", Jpn. J. Appl. Phys., Vol. 34, pp. 1322-1324 (1995) |
| | AK | |
| | AL | |
| | AM | |
| | AN | |
| | AO | |
| | | |

EXAMINER**DATE CONSIDERED**

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

**ANNEXE AU RAPPORT DE RECHERCHE PRÉLIMINAIRE
RELATIF A LA DEMANDE DE BREVET FRANÇAIS NO. FR 0303699 FA 632630**

La présente annexe indique les membres de la famille de brevets relatifs aux documents brevets cités dans le rapport de recherche préliminaire visé ci-dessus.

Les dits membres sont contenus au fichier informatique de l'Office européen des brevets à la date **d03-12-2003**

Les renseignements fournis sont donnés à titre indicatif et n'engagent pas la responsabilité de l'Office européen des brevets, ni de l'Administration française

| Document brevet cité au rapport de recherche | | Date de publication | Membre(s) de la famille de brevet(s) | Date de publication |
|---|----|------------------------|--|--|
| EP 0971396 | A | 12-01-2000 | JP 3385972 B2 JP 2000030992 A EP 0971396 A1 KR 2000011625 A US 6312797 B1 | 10-03-2003 28-01-2000 12-01-2000 25-02-2000 06-11-2001 |
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